Lattice Semiconductor Corporation - LFE2-12SE-7QN208C Datasheet

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Active
Number of LABs/CLBs	1500
Number of Logic Elements/Cells	12000
Total RAM Bits	226304
Number of I/O	131
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	208-BFQFP
Supplier Device Package	208-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfe2-12se-7qn208c

sysMEM Memory

LatticeECP2/M devices contains a number of sysMEM Embedded Block RAM (EBR). The EBR consists of an 18-Kbit RAM with dedicated input and output registers.

sysMEM Memory Block

The sysMEM block can implement single port, dual port or pseudo dual port memories. Each block can be used in a variety of depths and widths as shown in Table 2-6. FIFOs can be implemented in sysMEM EBR blocks by implementing support logic with PFUs. The EBR block facilitates parity checking by supporting an optional parity bit for each data byte. EBR blocks provide byte-enable support for configurations with18-bit and 36-bit data widths.

Table 2-6. sysMEM Block Configurations

Memory Mode	Configurations
Single Port	16,384 x 1 8,192 x 2 4,096 x 4 2,048 x 9 1,024 x 18 512 x 36
True Dual Port	16,384 x 1 8,192 x 2 4,096 x 4 2,048 x 9 1,024 x 18
Pseudo Dual Port	16,384 x 1 8,192 x 2 4,096 x 4 2,048 x 9 1,024 x 18 512 x 36

Bus Size Matching

All of the multi-port memory modes support different widths on each of the ports. The RAM bits are mapped LSB word 0 to MSB word 0, LSB word 1 to MSB word 1, and so on. Although the word size and number of words for each port varies, this mapping scheme applies to each port.

RAM Initialization and ROM Operation

If desired, the contents of the RAM can be pre-loaded during device configuration. By preloading the RAM block during the chip configuration cycle and disabling the write controls, the sysMEM block can also be utilized as a ROM.

Memory Cascading

Larger and deeper blocks of RAM can be created using EBR sysMEM Blocks. Typically, the Lattice design tools cascade memory transparently, based on specific design inputs.

Single, Dual and Pseudo-Dual Port Modes

In all the sysMEM RAM modes the input data and address for the ports are registered at the input of the memory array. The output data of the memory is optionally registered at the output.

EBR memory supports two forms of write behavior for single port or dual port operation:

1. Normal – Data on the output appears only during a read cycle. During a write cycle, the data (at the current address) does not appear on the output. This mode is supported for all data widths.

If an EBR is pre-loaded during configuration, the GSR input must be disabled or the release of the GSR during device Wake Up must occur before the release of the device I/Os becomes active.

These instructions apply to all EBR RAM and ROM implementations.

Note that there are no reset restrictions if the EBR synchronous reset is used and the EBR GSR input is disabled.

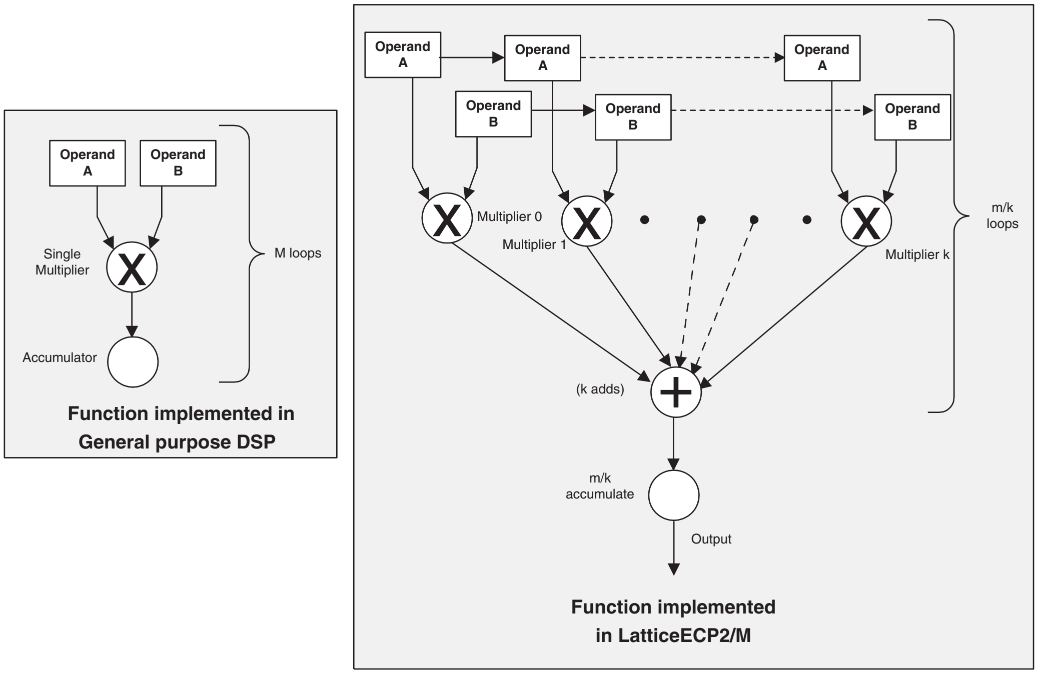
sysDSP™ Block

The LatticeECP2/M family provides a sysDSP block, making it ideally suited for low cost, high performance Digital Signal Processing (DSP) applications. Typical functions used in these applications are Finite Impulse Response (FIR) filters, Fast Fourier Transforms (FFT) functions, Correlators, Reed-Solomon/Turbo/Convolution encoders and decoders. These complex signal processing functions use similar building blocks such as multiply-adders and multiply-accumulators.

sysDSP Block Approach Compared to General DSP

Conventional general-purpose DSP chips typically contain one to four (Multiply and Accumulate) MAC units with fixed data-width multipliers; this leads to limited parallelism and limited throughput. Their throughput is increased by higher clock speeds. The LatticeECP2/M, on the other hand, has many DSP blocks that support different data-widths. This allows the designer to use highly parallel implementations of DSP functions. The designer can optimize the DSP performance vs. area by choosing an appropriate level of parallelism. Figure 2-22 compares the fully serial and the mixed parallel and serial implementations.

Figure 2-22. Comparison of General DSP and LatticeECP2/M Approaches



sysDSP Block Capabilities

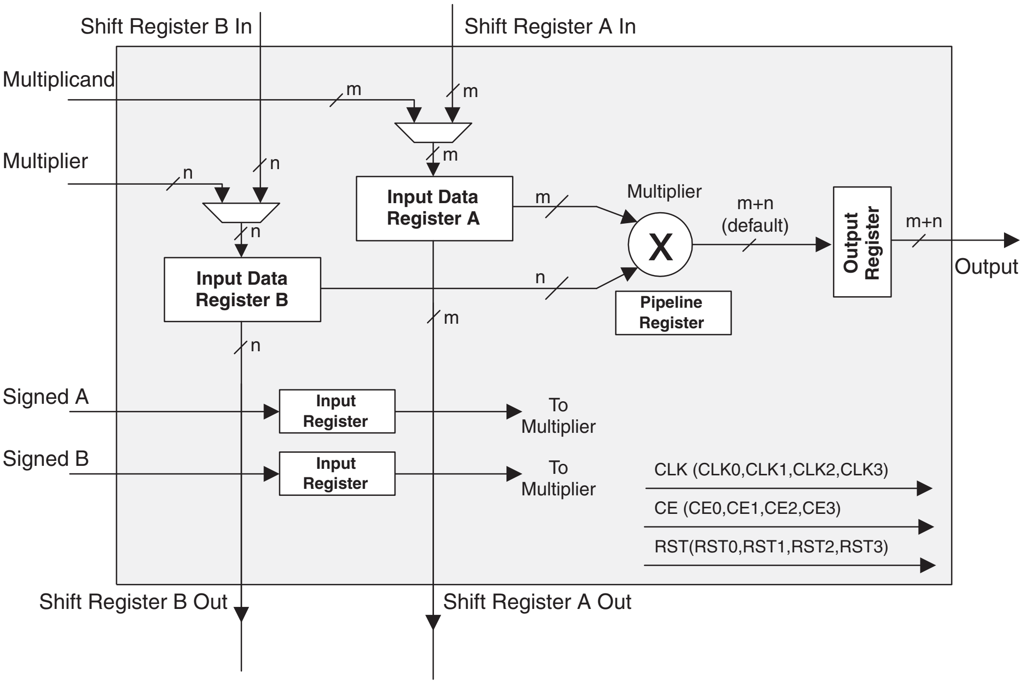
The sysDSP block in the LatticeECP2/M family supports four functional elements in three 9, 18 and 36 data path widths. The user selects a function element for a DSP block and then selects the width and type (signed/unsigned) of its operands. The operands in the LatticeECP2/M family sysDSP Blocks can be either signed or unsigned but not mixed within a function element. Similarly, the operand widths cannot be mixed within a block. In the LatticeECP2/M family the DSP elements can be concatenated.

The resources in each sysDSP block can be configured to support the following elements:

MULT sysDSP Element

This multiplier element implements a multiply with no addition or accumulator nodes. The two operands, A and B, are multiplied and the result is available at the output. The user can enable the input/output and pipeline registers. Figure 2-23 shows the MULT sysDSP element.

Figure 2-23. MULT sysDSP Element



O standards (together with their supply and reference voltages) supported by LatticeECP2/M devices. For further information about utilizing the sysI/O buffer to support a variety of standards please see the the list of additional technical information at the end of this data sheet.

Table 2-13. Supported Input Standards

Input Standard	V_{REF} (Nom.)	V_{CCIO}[1] (Nom.)
Single Ended Interfaces		
LVTTL	—	—
LVCMOS33	—	—
LVCMOS25	—	—
LVCMOS18	—	1.8
LVCMOS15	—	1.5
LVCMOS12	—	—
PCI 33	—	3.3
HSTL18 Class I, II	0.9	—
HSTL15 Class I	0.75	—
SSTL3 Class I, II	1.5	—
SSTL2 Class I, II	1.25	—
SSTL18 Class I, II	0.9	—
Differential Interfaces		
Differential SSTL18 Class I, II	—	—
Differential SSTL2 Class I, II	—	—
Differential SSTL3 Class I, II	—	—
Differential HSTL15 Class I	—	—
Differential HSTL18 Class I, II	—	—
LVDS, MLVDS, LVPECL, BLVDS, RSDS	—	—

1 When not specified, V_{CCIO} can be set anywhere in the valid operating range (page 3-1).

DLL Timing

Over Recommended Operating Conditions

Parameter	Description	Min.	Typ.	Max.	Units
f_{REF}	Input reference clock frequency (on-chip or off-chip)	100	—	500	MHz
f_{FB}	Feedback clock frequency (on-chip or off-chip)	100	—	500	MHz
f_{CLKOP}[1]	Output clock frequency, CLKOP	100	—	500	MHz
f_{CLKOS}[2]	Output clock frequency, CLKOS	25	—	500	MHz
t_{PJIT}	Output clock period jitter (clean input)		—	250	ps p-p
t_{CYJIT}	Output clock cycle to cycle jitter (clean input)			250	ps p-p
t_{DUTY}	Output clock duty cycle (at 50% levels, 50% duty cycle input clock, 50% duty cycle circuit turned off, time reference delay mode)	35		65	%
$t_{DUTYTRD}$	Output clock duty cycle (at 50% levels, arbitrary duty cycle input clock, 50% duty cycle circuit enabled, time reference delay mode)	40		60	%
$t_{DUTYCIR}$	Output clock duty cycle (at 50% levels, arbitrary duty cycle input clock, 50% duty cycle circuit enabled, clock injection removal mode)	40		60	%
t_{SKEW}[3]	Output clock to clock skew between two outputs with the same phase setting	—	—	100	ps
t_{PWH}	Input clock minimum pulse width high (at 80% level)	750	—	—	ps
t_{PWL}	Input clock minimum pulse width low (at 20% level)	750	—	—	ps
t_{INSTB}	Input clock period jitter	—	—	+/-250	ps
t_{LOCK}	DLL lock time	18,500	—	—	cycles
t_{RSWD}	Digital reset minimum pulse width (at 80% level)	3	—	—	ns
t_{PA}	Delay step size	16.5	42	59.4	ps
t_{RANGE1}	Max. delay setting for single delay block (144 taps)	2.376	6	8.553	ns
t_{RANGE4}	Max. delay setting for four chained delay blocks	9.504	24	34.214	ns

1. CLKOP runs at the same frequency as the input clock.
2. CLKOS minimum frequency is obtained with divide by 4.
3. This is intended to be a “path-matching” design guideline and is not a measurable specification.

SERDES External Reference Clock (LatticeECP2M Family Only)

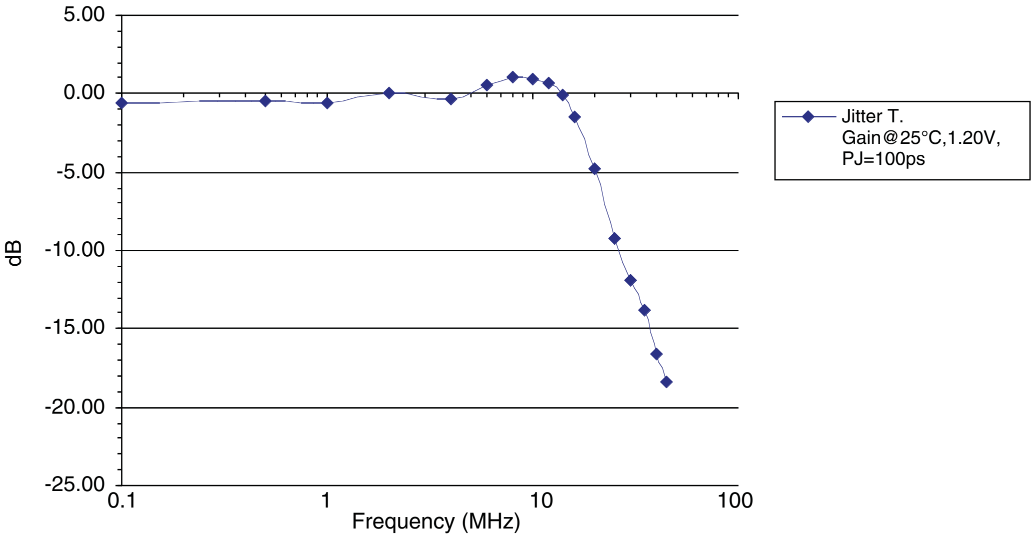
The external reference clock selection and its interface are a critical part of system applications for this product. Table 3-14 specifies reference clock requirements, over the full range of operating conditions.

Table 3-14. External Reference Clock Specification (refclkp/refclkn)

Symbol	Description	Min.	Typ.	Max.	Units
F_{REF}	Frequency range	25	—	320	MHz
$F_{REF-PPM}$	Frequency tolerance	-300	—	300	ppm
$V_{REF-IN-SE}$	Input swing, single-ended clock[1]	100	—	1200	mV, p-p
V_{REF-IN}	Input levels	0	—	V_{CCP} + 0.8	V
$V_{REF-CM-DC}$	Input common mode range (DC coupled)	0.5	—	1.2	V
$V_{REF-CM-AC}$	Input common mode range (AC coupled)[2]	0	—	1.5	V
D_{REF}	Duty cycle[3]	40	—	60	%
T_{REF-R}	Rise time (20% to 80%)		500	1000	ps
T_{REF-F}	Fall time (80% to 20%)		500	1000	ps
$Z_{REF-IN-TERM}$	Input termination		50/2K		Ohms
$C_{REF-IN-CAP}$	Input capacitance[4]	—	—	1.5	pF

1. The signal swing for a single-ended input clock must be as large as the p-p differential swing of a differential input clock to get the same gain at the input receiver. Lower swings for the clock may be possible, but will tend to increase jitter.
2. When AC coupled, the input common mode range is determined by:
   (Min input level) + (Peak-to-peak input swing)/2 ≤ (Input common mode voltage) ≤ (Max input level) - (Peak-to-peak input swing)/2
3. Measured at 50% amplitude.
4. Input capacitance of 1.5pF is total capacitance, including both device and package.

Figure 3-13. Jitter Transfer



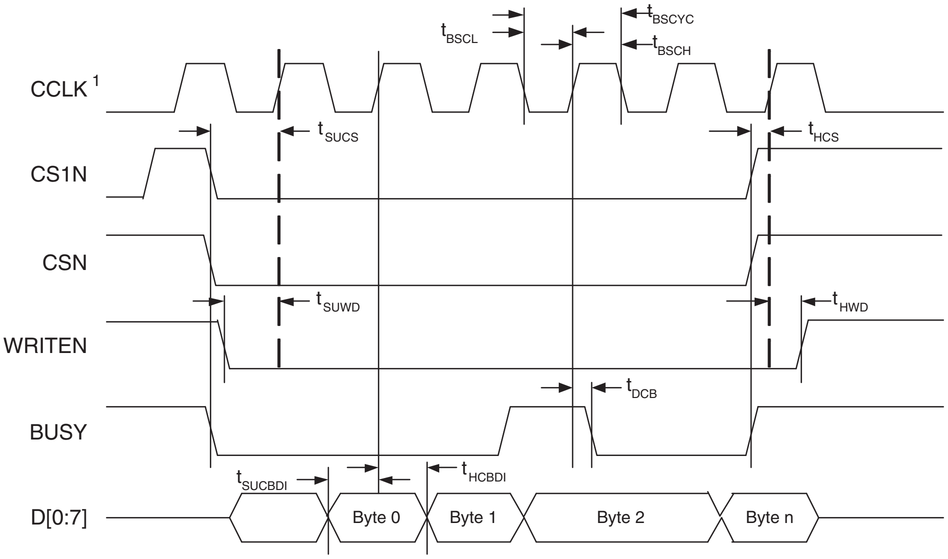
Note: This graph is for a nominal device.

SERDES Power-Down/Power-Up Specification

Table 3-15. Power-Down and Power-Up Specification

Symbol	Description	Max.	Units
t_{PWRDN}	Power-down time after all power down register bits set to ‘0’	10	µs
t_{PWRUP}	Power-up time after all power down register bits set to ‘1’	100	µs

Figure 3-15. sysCONFIG Parallel Port Write Cycle



1. In Master Parallel Mode the FPGA provides CCLK. In Slave Parallel Mode the external device provides CCLK.

Figure 3-16. sysCONFIG Slave Serial Port Timing

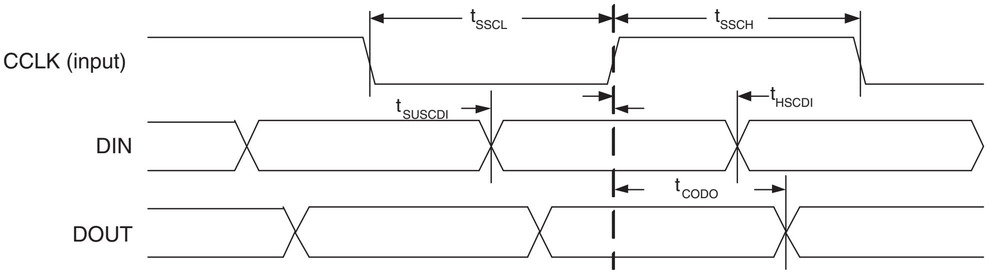
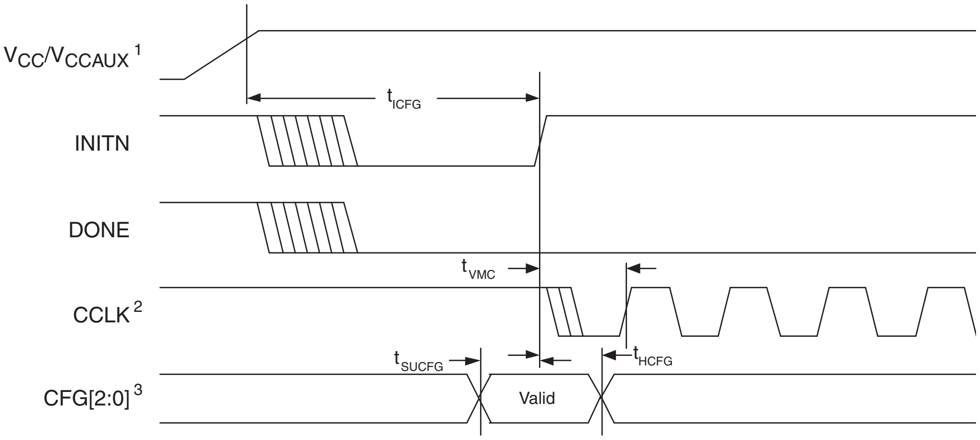


Figure 3-17. Power-On-Reset (POR) Timing



1. Time taken from V_{CC} or V_{CCAUX}, whichever is the last to reach its V_{MIN}.
2. Device is in a Master Mode.
3. The CFG pins are normally static (hard wired).

LFE2-6E/SE and LFE2-12E/SE Logic Signal Connections: 256 fpBGA (Cont.)

LFE2-6E/SE					LFE2-12E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
M8	PB8B	5	PCLKC5_0/BDQ6	C	PB26B	5	PCLKC5_0/BDQ24	C
GND	GNDIO5	-			GNDIO5	-		
P7	PB13A	4	PCLKT4_0/BDQ15	T	PB31A	4	PCLKT4_0/BDQ33	T
R8	PB13B	4	PCLKC4_0/BDQ15	C	PB31B	4	PCLKC4_0/BDQ33	C
VCCIO	VCCIO4	4			VCCIO4	4		
T5	PB14A	4	BDQ15	T	PB32A	4	BDQ33	T
T6	PB14B	4	BDQ15	C	PB32B	4	BDQ33	C
T8	PB15A	4	BDQS15	T	PB33A	4	BDQS33	T
GND	GNDIO4	-			GNDIO4	-		
R7	PB16A	4	BDQ15	T	PB34A	4	BDQ33	T
T9	PB15B	4	BDQ15	C	PB33B	4	BDQ33	C
T7	PB16B	4	BDQ15	C	PB34B	4	BDQ33	C
L8	PB17A	4	BDQ15	T	PB35A	4	BDQ33	T
VCCIO	VCCIO4	4			VCCIO4	4		
P8	PB18A	4	BDQ15	T	PB36A	4	BDQ33	T
L9	PB17B	4	BDQ15	C	PB35B	4	BDQ33	C
N8	PB18B	4	BDQ15	C	PB36B	4	BDQ33	C
R9	PB19A	4	BDQ15	T	PB37A	4	BDQ33	T
GND	GNDIO4	-			GNDIO4	-		
R10	PB19B	4	BDQ15	C	PB37B	4	BDQ33	C
-	-	-			VCCIO	4		
-	-	-			GNDIO4	4		
N9	PB20A	4	BDQ24	T	PB47A	4	BDQ51	T
T10	PB21A	4	BDQ24	T	PB48A	4	BDQ51	T
M9	PB20B	4	BDQ24	C	PB47B	4	BDQ51	C
R11	PB21B	4	BDQ24	C	PB48B	4	BDQ51	C
P10	PB22A	4	BDQ24	T	PB49A	4	BDQ51	T
N11	PB23A	4	BDQ24	T	PB50A	4	BDQ51	T
VCCIO	VCCIO4	4			VCCIO4	4		
N10	PB22B	4	BDQ24	C	PB49B	4	BDQ51	C
P11	PB23B	4	BDQ24	C	PB50B	4	BDQ51	C
T11	PB24A	4	BDQS24	T	PB51A	4	BDQS51	T
GND	GNDIO4	-			GNDIO4	-		
M11	PB25A	4	BDQ24	T	PB52A	4	BDQ51	T
T12	PB24B	4	BDQ24	C	PB51B	4	BDQ51	C
L11	PB25B	4	BDQ24	C	PB52B	4	BDQ51	C
T13	PB26A	4	BDQ24	T	PB53A	4	BDQ51	T
R13	PB27A	4	BDQ24	T	PB54A	4	BDQ51	T
VCCIO	VCCIO4	4			VCCIO4	4		
T14	PB26B	4	BDQ24	C	PB53B	4	BDQ51	C
P13	PB27B	4	BDQ24	C	PB54B	4	BDQ51	C
GND	GNDIO4	-			GNDIO4	-		
N12	PB28A	4	VREF2_4/BDQ24	T	PB55A	4	VREF2_4/BDQ51	T
M12	PB28B	4	VREF1_4/BDQ24	C	PB55B	4	VREF1_4/BDQ51	C
R15	CFG2	8			CFG2	8		

LFE2-12E/SE and LFE2-20E/SE Logic Signal Connections: 484 fpBGA (Cont.)

	LFE2-12E/12SE				LFE2-20E/20SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
A6	PT21A	0		T	PT30A	0		T
GNDIO	GNDIO0	-			GNDIO0	-		
C7	PT17B	0		C	PT26B	0		C
D10	PT18B	0		C	PT27B	0		C
C6	PT17A	0		T	PT26A	0		T
E10	PT18A	0		T	PT27A	0		T
VCCIO	VCCIO0	0			VCCIO0	0		
F10	PT15B	0		C	PT24B	0		C
B6	PT16B	0		C	PT25B	0		C
D9	PT15A	0		T	PT24A	0		T
B5	PT16A	0		T	PT25A	0		T
GNDIO	GNDIO0	-			GNDIO0	-		
A5	PT13B	0		C	PT22B	0		C
F9	PT14B	0		C	PT23B	0		C
A4	PT13A	0		T	PT22A	0		T
E9	PT14A	0		T	PT23A	0		T
VCCIO	VCCIO0	0			VCCIO0	0		
G8	PT11B	0		C	PT20B	0		C
A3	PT12B	0		C	PT21B	0		C
E8	PT11A	0		T	PT20A	0		T
A2	PT12A	0		T	PT21A	0		T
GNDIO	GNDIO0	-			GNDIO0	-		
-	-	-			VCCIO0	0		
C3	PT10B	0		C	PT10B	0		C
B3	PT10A	0		T	PT10A	0		T
-	-	-			GNDIO0	-		
E7	PT8B	0		C	PT8B	0		C
F8	PT9B	0		C	PT9B	0		C
F7	PT8A	0		T	PT8A	0		T
D7	PT9A	0		T	PT9A	0		T
VCCIO	VCCIO0	0			VCCIO0	0		
D4	PT6B	0		C	PT6B	0		C
D5	PT7B	0		C	PT7B	0		C
C4	PT6A	0		T	PT6A	0		T
D6	PT7A	0		T	PT7A	0		T
GNDIO	GNDIO0	-			GNDIO	-		
J7	PT4B	0		C	PT4B	0		C
B2	PT5B	0		C	PT5B	0		C
H7	PT4A	0		T	PT4A	0		T
B1	PT5A	0		T	PT5A	0		T
VCCIO	VCCIO0	0			VCCIO0	0		
D1	PT2B	0	VREF2_0	C	PT2B	0	VREF2_0	C
D3	PT3B	0		C	PT3B	0		C
C1	PT2A	0	VREF1_0	T	PT2A	0	VREF1_0	T

LFE2-20E/SE and LFE2-35E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2-20E/20SE					LFE2-35E/35SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
GND	GNDIO2	-			GNDIO2	-		
L21	PR18B	2	RDQ16	C (LVDS)*	PR24B	2	RDQ22	C (LVDS)*
K22	PR18A	2	RDQ16	T (LVDS)*	PR24A	2	RDQ22	T (LVDS)*
M24	PR17B	2	RDQ16	C	PR23B	2	RDQ22	C
N23	PR17A	2	RDQ16	T	PR23A	2	RDQ22	T
VCCIO	VCCIO2	2			VCCIO2	2		
K26	PR16B	2	RDQ16	C (LVDS)*	PR22B	2	RDQ22	C (LVDS)*
K25	PR16A	2	RDQS16	T (LVDS)*	PR22A	2	RDQS22	T (LVDS)*
M20	PR15B	2	RDQ16	C	PR21B	2	RDQ22	C
GND	GNDIO2	-			GNDIO2	-		
M19	PR15A	2	RDQ16	T	PR21A	2	RDQ22	T
L22	PR14B	2	RDQ16	C (LVDS)*	PR20B	2	RDQ22	C (LVDS)*
M22	PR14A	2	RDQ16	T (LVDS)*	PR20A	2	RDQ22	T (LVDS)*
K21	PR13B	2	RDQ16	C	PR19B	2	RDQ22	C
VCCIO	VCCIO2	2			VCCIO2	2		
M21	PR13A	2	RDQ16	T	PR19A	2	RDQ22	T
K24	PR12B	2	RDQ16	C (LVDS)*	PR18B	2	RDQ22	C (LVDS)*
J24	PR12A	2	RDQ16	T (LVDS)*	PR18A	2	RDQ22	T (LVDS)*
GND	GNDIO2	-			GNDIO2	-		
VCCIO	VCCIO2	2			VCCIO2	2		
L20	VCC	-			NC	-		
GND	GNDIO2	-			GNDIO2	-		
J26	NC	-			NC	-		
J25	NC	-			NC	-		
J23	NC	-			NC	-		
K23	NC	-			NC	-		
VCCIO	VCCIO2	2			VCCIO2	2		
H26	NC	-			NC	-		
H25	NC	-			NC	-		
H24	NC	-			NC	-		
GND	GNDIO2	-			GNDIO2	-		
H23	NC	-			NC	-		
VCCIO	VCCIO2	2			VCCIO2	2		
G26	PR11B	2	RDQ8	C	PR17B	2	RDQ14	C
GND	GNDIO2	-			GNDIO2	-		
G25	PR11A	2	RDQ8	T	PR17A	2	RDQ14	T
F26	PR10B	2	RDQ8	C (LVDS)*	PR16B	2	RDQ14	C (LVDS)*
F25	PR10A	2	RDQ8	T (LVDS)*	PR16A	2	RDQ14	T (LVDS)*
K20	PR9B	2	RDQ8	C	PR15B	2	RDQ14	C
VCCIO	VCCIO2	2			VCCIO2	2		
L19	PR9A	2	RDQ8	T	PR15A	2	RDQ14	T
E26	PR8B	2	RDQ8	C (LVDS)*	PR14B	2	RDQ14	C (LVDS)*
E25	PR8A	2	RDQS8	T (LVDS)*	PR14A	2	RDQS14	T (LVDS)*
GND	GNDIO2	-			GNDIO2	-		
J22	PR7B	2	RDQ8	C	PR13B	2	RDQ14	C
H22	PR7A	2	RDQ8	T	PR13A	2	RDQ14	T

LFE2-20E/SE and LFE2-35E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2-20E/20SE					LFE2-35E/35SE			
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
C20	PT57B	1		C	PT66B	1		C
D20	PT57A	1		T	PT66A	1		T
A22	PT56B	1		C	PT65B	1		C
A21	PT56A	1		T	PT65A	1		T
GND	GNDIO1	-			GNDIO1	-		
E19	NC	-			NC	-		
C19	NC	-			NC	-		
VCCIO	VCCIO1	1			VCCIO1	1		
B21	NC	-			NC	-		
B20	NC	-			NC	-		
D19	NC	-			NC	-		
B19	NC	-			NC	-		
GND	GNDIO1	-			GNDIO1	-		
G17	NC	-			NC	-		
E18	NC	-			NC	-		
G19	NC	-			NC	-		
F17	NC	-			NC	-		
VCCIO	VCCIO1	1			VCCIO1	1		
A20	NC	-			NC	-		
A19	NC	-			NC	-		
E17	NC	-			NC	-		
D18	NC	-			NC	-		
B18	PT55B	1		C	PT55B	1		C
GND	GNDIO1	-			GNDIO1	-		
A18	PT55A	1		T	PT55A	1		T
E16	PT54B	1		C	PT54B	1		C
G16	PT54A	1		T	PT54A	1		T
F16	PT53B	1		C	PT53B	1		C
VCCIO	VCCIO1	1			VCCIO1	1		
H18	PT53A	1		T	PT53A	1		T
A17	PT52B	1		C	PT52B	1		C
B17	PT52A	1		T	PT52A	1		T
C18	PT51B	1		C	PT51B	1		C
B16	PT51A	1		T	PT51A	1		T
C17	PT50B	1		C	PT50B	1		C
GND	GNDIO1	-			GNDIO1	-		
D17	PT50A	1		T	PT50A	1		T
E15	PT49B	1		C	PT49B	1		C
VCCIO	VCCIO1	1			VCCIO1	1		
G15	PT49A	1		T	PT49A	1		T
A16	PT48B	1		C	PT48B	1		C
B15	PT48A	1		T	PT48A	1		T
D15	PT47B	1		C	PT47B	1		C
F15	PT47A	1		T	PT47A	1		T
A14	PT46B	1		C	PT46B	1		C
B14	PT46A	1		T	PT46A	1		T

LFE2M50E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2M50E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
W19	NC	-		
W18	NC	-		
V17	NC	-		
V18	NC	-		
D15	NC	-		
G14	NC	-		
G15	NC	-		
D14	NC	-		
E15	NC	-		
E14	NC	-		
F15	NC	-		
F14	NC	-		
F13	NC	-		
G12	NC	-		
G13	NC	-		
H8	VCCPLL	-		
H15	VCCPLL	-		
R8	VCCPLL	-		
R15	VCCPLL	-		

* Supports true LVDS. Other differential signals must be emulated with external resistors.
** These dedicated input pins can be used for GPLLs or GDLLs within the respective quadrant.
***For density migration, board design must take into account that these sysCONFIG pins are dual function for the lower density devices (ECP2M20 and ECP2M35). They can be either sysCONFIG pins or general purpose I/Os. These pins are dedicated pins for the higher density devices (ECP2M50, ECP2M70 and ECP2M100).
****Due to packaging bond out option, this DQS does not have all the necessary DQ pins bonded out for a full 8-bit data width.

Note: VCCIO and GND pads are used to determine the average DC current drawn by I/Os between GND/VCCIO connections, or between the last GND/VCCIO in an I/O bank and the end of an I/O bank. The substrate pads listed in the Pin Table do not necessarily have a one to one connection with a package ball or pin.

LFE2M35E/SE and LFE2M50E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2M35E/SE					LFE2M50E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
P8	PL45A	6	LDQ48	T	PL49A	6	LDQ52	T
R6	PL45B	6	LDQ48	C	PL49B	6	LDQ52	C
VCCIO	VCCIO6	6			VCCIO6	6		
T1	PL46A	6	LDQ48	T (LVDS)*	PL50A	6	LDQ52	T*
U1	PL46B	6	LDQ48	C (LVDS)*	PL50B	6	LDQ52	C*
R7	PL47A	6	LDQ48	T	PL51A	6	LDQ52	T
T5	PL47B	6	LDQ48	C	PL51B	6	LDQ52	C
GNDIO	GNDIO6	-			GNDIO6	-		
U3	PL48A	6	LDQS48	T (LVDS)*	PL52A	6	LDQS52	T*
U4	PL48B	6	LDQ48	C (LVDS)*	PL52B	6	LDQ52	C*
U5	PL49A	6	LDQ48	T	PL53A	6	LDQ52	T
VCCIO	VCCIO6	6			VCCIO6	6		
U6	PL49B	6	LDQ48	C	PL53B	6	LDQ52	C
U2	PL50A	6	LDQ48	T (LVDS)*	PL54A	6	LDQ52	T*
V1	PL50B	6	LDQ48	C (LVDS)*	PL54B	6	LDQ52	C*
W2	PL51A	6	LDQ48	T	PL55A	6	LDQ52	T
GNDIO	GNDIO6	-			GNDIO6	-		
V2	PL51B	6	LDQ48	C	PL55B	6	LDQ52	C
V4	PL55A	6	LDQ57	T (LVDS)*	PL59A	6		T*
VCCIO	VCCIO6	6			VCCIO6	6		
V3	PL55B	6	LDQ57	C (LVDS)*	PL59B	6		C*
-	-	-			GNDIO6	-		
W4	PL57A	6	LLM0_GPLLT_IN_A**/LDQS57****	T (LVDS)*	PL62A	6	LLM0_GPLLT_IN_A	T*
GNDIO	GNDIO6	-			GNDIO6	-		
W3	PL57B	6	LLM0_GPLLC_IN_A**/LDQ57	C (LVDS)*	PL62B	6	LLM0_GPLLC_IN_A	C*
W1	PL58A	6	LLM0_GPLLT_FB_A/LDQ57	T	PL63A	6	LLM0_GPLLT_FB_A	T
Y1	PL58B	6	LLM0_GPLLC_FB_A/LDQ57	C	PL63B	6	LLM0_GPLLC_FB_A	C
VCCIO	VCCIO6	6			VCCIO6	6		
AA1	PL59A	6	LLM0_GDLLT_IN_A**/LDQ57	T (LVDS)*	PL64A	6	LLM0_GDLLT_IN_A	T*
AB1	PL59B	6	LLM0_GDLLC_IN_A**/LDQ57	C (LVDS)*	PL64B	6	LLM0_GDLLC_IN_A	C*
U7	PL60A	6	LLM0_GDLLT_FB_A/LDQ57	T	PL65A	6	LLM0_GDLLT_FB_A	T
V6	PL60B	6	LLM0_GDLLC_FB_A/LDQ57	C	PL65B	6	LLM0_GDLLC_FB_A	C
GNDIO	GNDIO6	-			GNDIO6	-		
T8	LLM0_PLLCAP	6			LLM0_PLLCAP	6		
W5	PL62A	6	LDQ66	T (LVDS)*	PL67A	6	LDQ71	T*
Y4	PL62B	6	LDQ66	C (LVDS)*	PL67B	6	LDQ71	C*
U8	PL63A	6	LDQ66	T	PL68A	6	LDQ71	T
W6	PL63B	6	LDQ66	C	PL68B	6	LDQ71	C
VCCIO	VCCIO6	6			VCCIO6	6		
Y3	PL64A	6	LDQ66	T (LVDS)*	PL69A	6	LDQ71	T*
AA3	PL64B	6	LDQ66	C (LVDS)*	PL69B	6	LDQ71	C*
V7	NC	-			PL70A	6	LDQ71	T
Y5	PL65B	6	LDQ66	C	PL70B	6	LDQ71	C
GNDIO	GNDIO6	-			GNDIO6	-		
AB2	PL66A	6	LDQS66	T (LVDS)*	PL71A	6	LDQS71	T*
AA4	PL66B	6	LDQ66	C (LVDS)*	PL71B	6	LDQ71	C*
Y6	PL67A	6	LDQ66	T	PL72A	6	LDQ71	T
VCCIO	VCCIO6	6			VCCIO6	6		

LFE2M50E/SE and LFE2M70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M50E/SE					LFE2M70E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
K3	VCCIO7	7			VCCIO7	7		
M10	VCCIO7	7			VCCIO7	7		
M7	VCCIO7	7			VCCIO7	7		
N10	VCCIO7	7			VCCIO7	7		
N3	VCCIO7	7			VCCIO7	7		
P10	VCCIO7	7			VCCIO7	7		
R6	VCCIO7	7			VCCIO7	7		
AA25	VCCIO8	8			VCCIO8	8		
AD28	VCCIO8	8			VCCIO8	8		
AA10	VCCAUX	-			VCCAUX	-		
AA11	VCCAUX	-			VCCAUX	-		
AA20	VCCAUX	-			VCCAUX	-		
AA21	VCCAUX	-			VCCAUX	-		
K10	VCCAUX	-			VCCAUX	-		
K11	VCCAUX	-			VCCAUX	-		
K20	VCCAUX	-			VCCAUX	-		
K21	VCCAUX	-			VCCAUX	-		
L10	VCCAUX	-			VCCAUX	-		
L11	VCCAUX	-			VCCAUX	-		
L20	VCCAUX	-			VCCAUX	-		
L21	VCCAUX	-			VCCAUX	-		
Y10	VCCAUX	-			VCCAUX	-		
Y11	VCCAUX	-			VCCAUX	-		
Y20	VCCAUX	-			VCCAUX	-		
Y21	VCCAUX	-			VCCAUX	-		
A1	GND	-			GND	-		
A13	GND	-			GND	-		
A18	GND	-			GND	-		
A24	GND	-			GND	-		
A30	GND	-			GND	-		
A7	GND	-			GND	-		
AA14	GND	-			GND	-		
AA15	GND	-			GND	-		
AA16	GND	-			GND	-		
AA17	GND	-			GND	-		
AA24	GND	-			GND	-		
AA27	GND	-			GND	-		
AA4	GND	-			GND	-		
AB24	GND	-			GND	-		
AB7	GND	-			GND	-		
AD12	GND	-			GND	-		
AD19	GND	-			GND	-		
AD27	GND	-			GND	-		
AE22	GND	-			GND	-		
AE27	GND	-			GND	-		
AE4	GND	-			GND	-		
AE9	GND	-			GND	-		
AF14	GND	-			GND	-		

LFE2M50E/SE and LFE2M70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

	LFE2M50E/SE				LFE2M70E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
G7	PL8A	7	LDQ6	T (LVDS)*	NC	-		
G8	PL6A	7	LDQS6****	T (LVDS)*	NC	-		
G9	PL5A	7	LDQ6	T	NC	-		
H19	NC	-			NC	-		
H20	NC	-			NC	-		
H21	NC	-			NC	-		
H22	NC	-			NC	-		
H6	PL8B	7	LDQ6	C (LVDS)*	NC	-		
H8	PL5B	7	LDQ6	C	NC	-		
H9	PL2A	7	LDQ6	T (LVDS)*	NC	-		
J10	PL2B	7	LDQ6	C (LVDS)*	NC	-		
J20	NC	-			NC	-		
J21	NC	-			NC	-		
J9	PL4A	7	LDQ6	T (LVDS)*	NC	-		
K9	PL4B	7	LDQ6	C (LVDS)*	NC	-		
R9	NC	-			NC	-		
U22	NC	-			NC	-		
W9	NC	-			NC	-		
N13	VCCPLL	-			VCCPLL	-		
N18	VCCPLL	-			VCCPLL	-		
V13	VCCPLL	-			VCCPLL	-		
V18	VCCPLL	-			VCCPLL	-		

* Supports true LVDS. Other differential signals must be emulated with external resistors.

** These dedicated input pins can be used for GPLLs or GDLLs within the respective quadrant.

*** These sysCONFIG pins are dedicated I/O pins for configuration. The outpus are actively driven during normal device operation.

****Due to packaging bond out option, this DQS does not have all the necessary DQ pins bonded out for a full 8-bit data width.

Note: VCCIO and GND pads are used to determine the average DC current drawn by I/Os between GND/VCCIO connections, or between the last GND/VCCIO in an I/O bank and the end of an I/O bank. The substrate pads listed in the Pin Table do not necessarily have a one to one connection with a package ball or pin.

LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M100E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
K26	PR26A	2	RDQ23	T
K23	PR25B	2	RDQ23	C (LVDS)*
K22	PR25A	2	RDQ23	T (LVDS)*
J22	PR24B	2	RDQ23	C
VCCIO	VCCIO2	2		
J23	PR24A	2	RDQ23	T
GNDIO	GNDIO2	-		
VCCIO	VCCIO2	2		
J26	PR17B	2	RDQ15	C (LVDS)*
H26	PR17A	2	RDQ15	T (LVDS)*
H27	PR16B	2	RDQ15	C
G26	PR16A	2	RDQ15	T
VCCIO	VCCIO2	2		
H23	PR15B	2	RDQ15	C (LVDS)*
H24	PR15A	2	RDQS15	T (LVDS)*
D28	PR14B	2	RDQ15	C
GNDIO	GNDIO2	-		
E28	PR14A	2	RDQ15	T
G24	PR13B	2	RDQ15	C (LVDS)*
H25	PR13A	2	RDQ15	T (LVDS)*
D27	PR12B	2	RUM0_SPLLC_FB_A/RDQ15	C
VCCIO	VCCIO2	2		
E27	PR12A	2	RUM0_SPLLT_FB_A/RDQ15	T
F26	PR11B	2	RUM0_SPLLC_IN_A/RDQ15	C (LVDS)*
G25	PR11A	2	RUM0_SPLLT_IN_A/RDQ15	T (LVDS)*
F24	PR9B	2	VREF2_2	C
-	-	-		
GNDIO	GNDIO2	-		
F25	PR9A	2	VREF1_2	T
VCCIO	VCCIO2	2		
G23	XRES	1		
C30	URC_SQ_VCCRX0	12		
A29	URC_SQ_HDINP0	12		T
B30	URC_SQ_VCCIB0	12		
B29	URC_SQ_HDINN0	12		C
C27	URC_SQ_VCCTX0	12		
A26	URC_SQ_HDOUTP0	12		T
A27	URC_SQ_VCCOB0	12		
B26	URC_SQ_HDOUTN0	12		C
C26	URC_SQ_VCCTX1	12		
B25	URC_SQ_HDOUTN1	12		C
C25	URC_SQ_VCCOB1	12		
A25	URC_SQ_HDOUTP1	12		T

LFE2M70E/SE and LFE2M100E/SE Logic Signal Connections: 1152 fpBGA (Cont.)

	LFE2M70E/SE				LFE2M100E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
E4	NC	-			NC	-		
E9	NC	-			NC	-		
F10	NC	-			NC	-		
F25	NC	-			NC	-		
F26	NC	-			NC	-		
F27	NC	-			NC	-		
F28	NC	-			NC	-		
F29	NC	-			NC	-		
F30	NC	-			NC	-		
F31	NC	-			NC	-		
F32	NC	-			NC	-		
F33	NC	-			NC	-		
F34	NC	-			NC	-		
F5	NC	-			NC	-		
F6	NC	-			NC	-		
F7	NC	-			NC	-		
F8	NC	-			NC	-		
F9	NC	-			NC	-		
G10	NC	-			NC	-		
G11	NC	-			NC	-		
G24	NC	-			NC	-		
G25	NC	-			NC	-		
G26	NC	-			NC	-		
G27	NC	-			NC	-		
G28	NC	-			NC	-		
G29	NC	-			NC	-		
G30	NC	-			NC	-		
G33	NC	-			NC	-		
G34	NC	-			NC	-		
G7	NC	-			NC	-		
G8	NC	-			NC	-		
G9	NC	-			NC	-		
H10	NC	-			NC	-		
H11	NC	-			NC	-		
H24	NC	-			NC	-		
H25	NC	-			NC	-		
H26	NC	-			NC	-		
H27	NC	-			NC	-		
H28	NC	-			NC	-		
H29	NC	-			NC	-		
H8	NC	-			NC	-		
H9	NC	-			NC	-		
J10	NC	-			NC	-		
J11	NC	-			NC	-		
J24	NC	-			NC	-		
J25	NC	-			NC	-		
J26	NC	-			NC	-		
J9	NC	-			NC	-		
K10	NC	-			NC	-		

LatticeECP2/M Family Data Sheet
Ordering Information

July 2012 **Data Sheet DS1006**

LatticeECP2 Part Number Description

LFE2 – XX XE – X XXXXXX X

Device Family
ECP2 (LatticeECP2 FPGA)

Logic Capacity
6 = 6K LUTs
12 = 12K LUTs
20 = 20K LUTs
35 = 35K LUTs
50 = 50K LUTs
70 = 70K LUTs

Encryption
S = Security Series (Encryption Feature)
Blank = Standard Series (No Encryption)

Supply Voltage
E = 1.2V

Grade
C = Commercial
I = Industrial

Package
T144 = 144-pin TQFP
Q208 = 208-pin PQFP
F256 = 256-ball fpBGA
F484 = 484-ball fpBGA
F672 = 672-ball fpBGA
F900 = 900-ball fpBGA

TN144 = 144-pin Lead-Free TQFP
QN208 = 208-pin Lead-Free PQFP
FN256 = 256-ball Lead-Free fpBGA
FN484 = 484-ball Lead-Free fpBGA
FN672 = 672-ball Lead-Free fpBGA
FN900 = 900-ball Lead-Free fpBGA

Speed
5 = Slowest
6
7 = Fastest

Ordering Information

Note:þLatticeECP2 devices are dual marked. For example, the commercial speed grade LFE2-50E-7F672C is also marked with industrial grade -6I (LFE2-50E-6F672I). The commercial grade is one speed grade faster than the associated dual mark industrial grade. The slowest commercial speed grade does not have industrial markings. The markings appear as follows:

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M100SE-5FN1152C	520	1.2V	-5	Lead-Free fpBGA	1152	Com	100
LFE2M100SE-6FN1152C	520	1.2V	-6	Lead-Free fpBGA	1152	Com	100
LFE2M100SE-7FN1152C	520	1.2V	-7	Lead-Free fpBGA	1152	Com	100
LFE2M100SE-5FN900C	416	1.2V	-5	Lead-Free fpBGA	900	Com	100
LFE2M100SE-6FN900C	416	1.2V	-6	Lead-Free fpBGA	900	Com	100
LFE2M100SE-7FN900C	416	1.2V	-7	Lead-Free fpBGA	900	Com	100

Date	Version	Section	Change Summary
November 2009 (cont.)	03.5 (cont.)	Pinout Information (cont.)	LatticeECP2M Pin Information Summary, LFE2M50, LFE2M70 and LFE2M100 table - corrected values for LFE2M50, 672 fpBGA in Available DDR-Interfaces per I/O Bank.
			Minor corrections in LFE2M20E/SE and LFE2M35E/SE Logic Signal Connections: 484 fpBGA table.
			Minor corrections in LFE2M50E/SE and LFE2M70E/SE Logic Signal Connections: 900 fpBGA table.
			Minor corrections in LFE2M100E/SE Logic Signal Connections: 900 fpBGA table.
			Updated LFE2-6E/SE and LFE2-12E/SE Logical Signal Connections (changed D1/SPIDS to D1).
		Ordering Information	Updated LatticeECP2M Part Number Description diagram.
March 2010	03.6	DC and Switching Characteristics	Footnote for SED operating frequency added to the sysCONFIG Port Timing Specifications table.
		Pinout Information	Changed Dual Function pin E7 to be D7/SPDI0 in Logic Signal Connections tables. Changed footnote (***) in Logic Signal Connections table.
July 2010	03.7	Architecture	Updated the Typical sysIO Behavior During Power-up text section.
		Pinout Information	Added reference to powerup information.
			Corrected reference to footnote for pins 131 and 132 for the LFE-20E/SE, 208 PQFP.
			Referenced footnote (***) for all D7/SPID0.
			Changed D7*** to D7/SPID0.
			Corrected *** footnote.
		All Sections	Included references to Lattice Diamond design software wherever ispLEVER and ispLeverCORE is specified.
April 2011	03.8	DC and Switching Characteristics	DC Electrical Characteristics table: - Added footnote 3 to I_{IH} - Added footnote 2 to I_{IL}, I_{IH} - Updated C1 and C2 typ. and max. data.
			DLL Timing table – Removed line for t_R and t_F
			LatticeECP2/M sysCONFIG Port Timing Specifications table – added footnote to t_{DINIT}.
			Figure 3-18 – Corrected label to be PRGM (not PRGMRJ).
		Pinout Information	LFE2-12E/SE and LFE-20/SE Logical Signal Connections for 208 PQFP – Corrected Dual Function information for pins 112, 114, 117, 119.
January 2012	03.9	Multiple	Removed references to ispLEVER design software.
		Architecture	Corrected information regarding SED support.
		DC and Switching Characteristics	Added reference to ESD information.
June 2013	04.0	All	Updated document with new corporate logo.
		Architecture	Architecture Overview – Added information on the state of the register on power up and after configuration.